12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240202002.1
Qualification of RFAB using qualified Process Technology, Die Revision and additional Assembly Site option for select devices
Change Notification / Sample Request

Date: February 02, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) process.

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team. For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

Change Management Team
SC Business Services

20240202002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LMC6772AIMM/NOPB	NULL
LMC6772AIMMX/NOPB	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240202002.1	PCN Date:	February 02, 2024
Title:	Qualification of RFAB using qualified Process Technology, Die Revision and additional Assembly Site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	May 2, 2024	Estimated Sample Availability:	Mar 2, 2024*

***Sample requests received after March 2, 2024 will not be supported.**

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Materials
☒	Packing/Shipping/ Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of RFAB using the LBC9 qualified process technology in addition to an Assembly site option for the devices listed below.

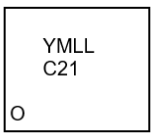
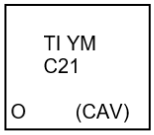
Current Fab Site			Additional Fab Site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab Site**	**Process**	**Wafer Diameter**
GFAB6/8	P2CMOS	150/200 mm	RFAB	LBC9	300 mm
DFAB		200 mm			

The die was also changed as a result of the process change.

Additionally, there will be Assembly site & BOM options introduced for these devices as follows:

	TIEM	MLA
Wire diam/type	0.96mil Cu	0.80 mil Cu
Mount compound	8075531	4147858
Mold Compound	8096859	4211880
Lead finish	Matte Sn	NiPdAu
ECAT	G3	G4

Package marking change:

	Current	Proposed
Package Marking (Sample)	 YM = YEAR MONTH DATE CODE LL = ASSEMBLY LOT CODE O = PIN 1 INDICATOR	 TI = TI LETTERS YM = YEAR MONTH DATE CODE O = PIN 1 INDICATOR CAV = CAVITY NUMBER

Qual details are provided in the Qual Data Section.

Reason for Change:

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive /

negative):
None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
GFAB6	GF6	GBR	Greenock
GFAB8	GF8	GBR	Greenock
DFAB	DLN	USA	Dallas
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
C	**C**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
TIEMA	CU6	MYS	Melaka
MLA	**MLA**	**MYS**	**Kuala Lumpur**

Sample product shipping label (not actual product label)

Product Affected:

LMC6772AIMM/NOPB	LMC6772AIMMX/NOPB

For alternate parts with similar or improved performance, please visit the product page on TI.com

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LMC6772AIMMX/NOPB	QBS Reference: OPA2205ADGKR	QBS Reference: OPA2206ADGKR	QBS Reference: BQ79616PAPRQ1	QBS Reference: TLV1812QDGKRQ1	QBS Reference: TLV1822QDGKRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	2/154/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	2/154/0	-	1/77/0	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	1/77/0	2/154/0	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	1/77/0	2/154/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	1/77/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	1/77/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	1/6/0
FTY	E6	Final Test Yield	-	-	Pass	-	-	-	-	-

- QBS: Qual By Similarity
- Qual Device LMC6772AIMMX/NOPB is qualified at MSL1 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2312-001

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.